



### POWER DISSIPATION (TO-252-5-P1)

This specification is at mounted on board. Power Dissipation ( $P_D$ ) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

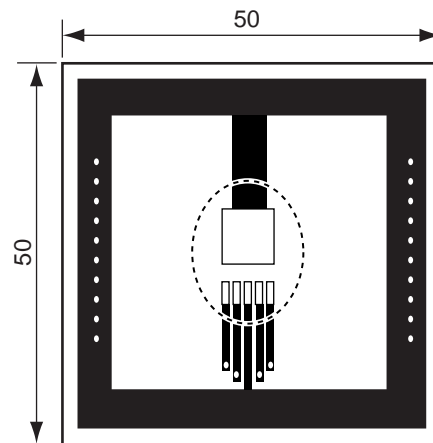
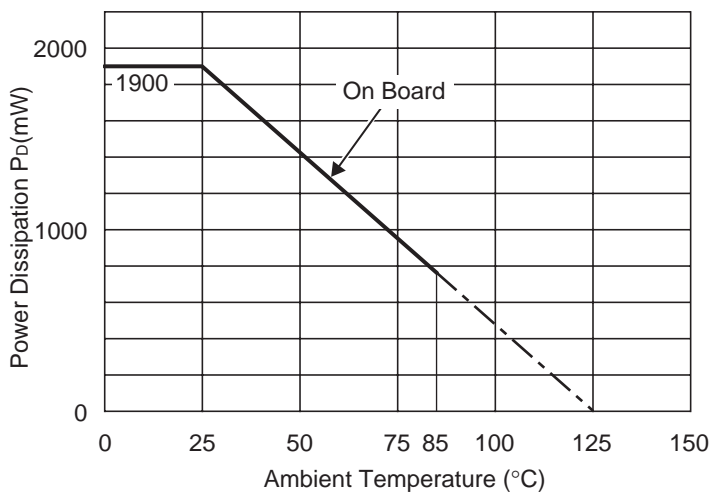
Measurement Conditions

	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)
Board Dimensions	50mm × 50mm × 1.6mm
Copper Ratio	Top side : Approx. 50% , Back side : Approx. 50%
Through-holes	φ0.5mm × 24pcs

Measurement Results

( $T_{opt}=25^{\circ}C$ ,  $T_{jmax}=125^{\circ}C$ )

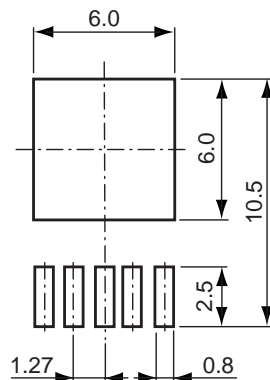
	Standard Land Pattern
Power Dissipation	1900mW
Thermal Resistance	$\theta_{ja}=(125-25^{\circ}C)/1.9W=53^{\circ}C/W$
	$\theta_{jc}=17^{\circ}C/W$



Measurement Board Pattern

○ IC Mount Area (Unit: mm)

### RECOMMENDED LAND PATTERN



(Unit: mm)